

ZXTP07012EFF

12V, SOT23F, PNP medium power transistor

Summary;

$BV_{CEO} > -12V$

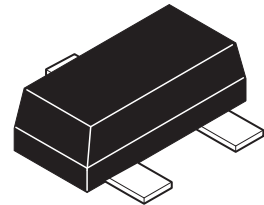
$I_{C(cont)} = -4A$

$V_{CE(sat)} < -75mV @ 1A$

$R_{CE(sat)} = 50m\Omega$

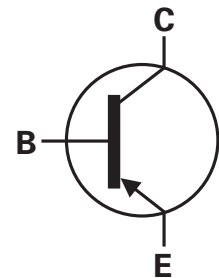
$P_D = 1.5W$

Complementary part number ZXTN07012EFF



Description

This low voltage PNP transistor has been designed for applications requiring high gain and very low saturation voltage. The SOT23F package is pin compatible with the industry standard SOT23 footprint but offers lower profile and higher dissipation for applications where power density is of utmost importance.

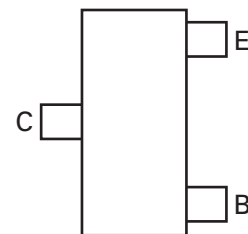


Features

- Low profile SOT23F package
- Low saturation voltage
- High gain
- High power dissipation

Applications

- Load switches
- Battery charging
- Motor drive



Pinout - top view

Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP07012EFFTA	7	8	3000

Device marking

1D1

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Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Collector-base voltage	V_{CBO}	-12	V
Collector-emitter voltage	V_{CEO}	-12	V
Emitter-base voltage	V_{EBO}	-7	V
Continuous collector current ^(c)	I_C	-4	A
Peak pulse current	I_{CM}	-8	A
Base current	I_B	-1	A
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(a)}$		0.84	W
Linear derating factor	P_D	6.72	mW/°C
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(b)}$		1.34	W
Linear derating factor	P_D	10.72	mW/°C
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(c)}$		1.50	W
Linear derating factor	P_D	12.0	mW/°C
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(d)}$		2.0	W
Linear derating factor	P_D	16.0	mW/°C
Operating and storage temperature range	T_j, T_{stg}	-55 to 150	°C

Thermal resistance

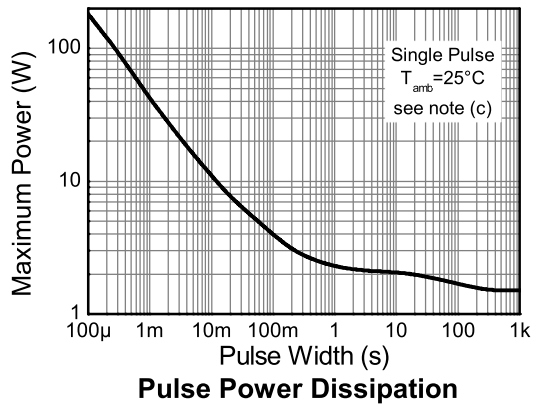
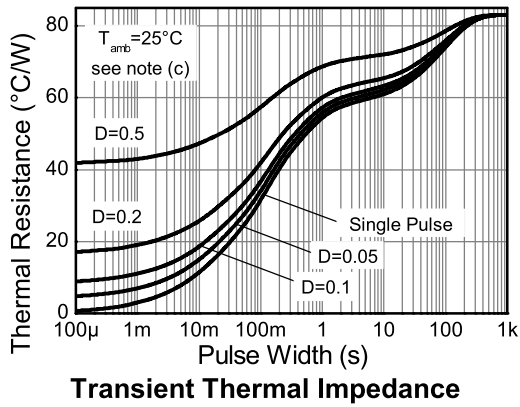
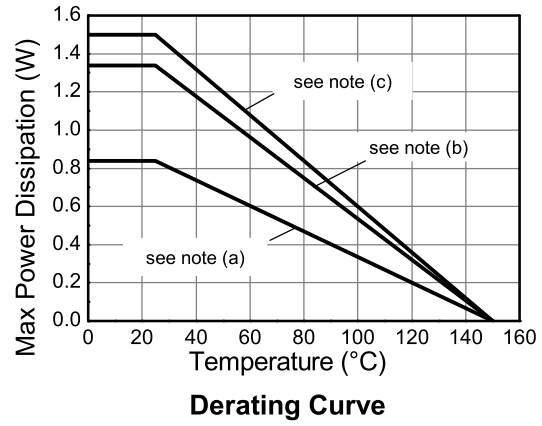
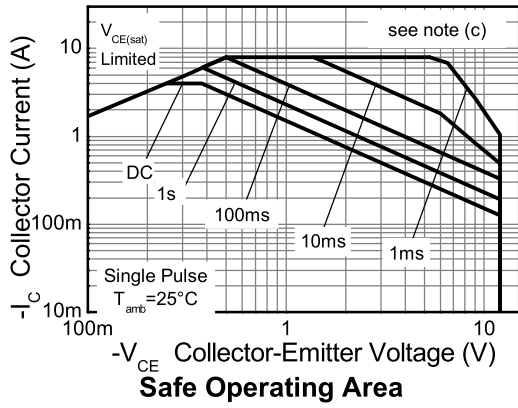
Parameter	Symbol	Limit	Unit
Junction to ambient ^(a)	$R_{\theta JA}$	149	°C/W
Junction to ambient ^(b)	$R_{\theta JA}$	93	°C/W
Junction to ambient ^(c)	$R_{\theta JA}$	83	°C/W
Junction to ambient ^(d)	$R_{\theta JA}$	60	°C/W

NOTES:

- (a) For a device surface mounted on 15mm x 15mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- (b) Mounted on 25mm x 25mm x 1.6mm FR4 PCB with a high coverage of single sided 2 oz copper in still air conditions.
- (c) Mounted on 50mm x 50mm x 1.6mm FR4 PCB with a high coverage of single sided 2 oz copper in still air conditions.
- (d) As (c) above measured at $t < 5$ secs.

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Characteristics



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Electrical characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

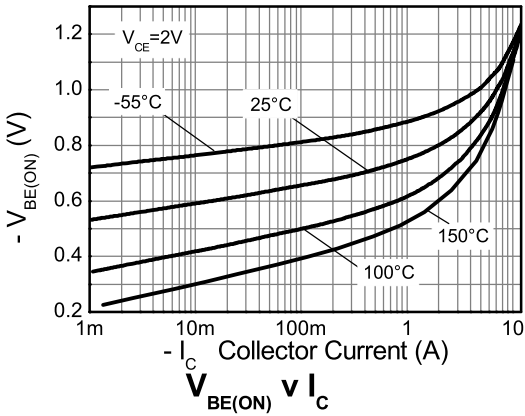
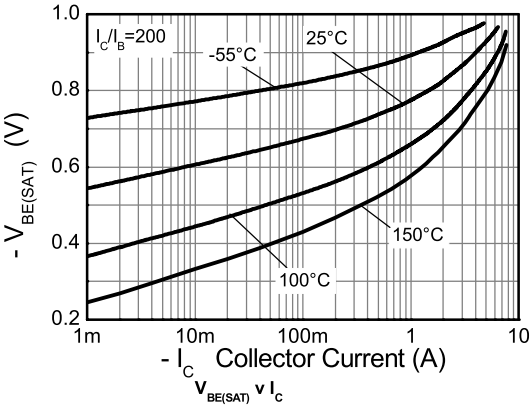
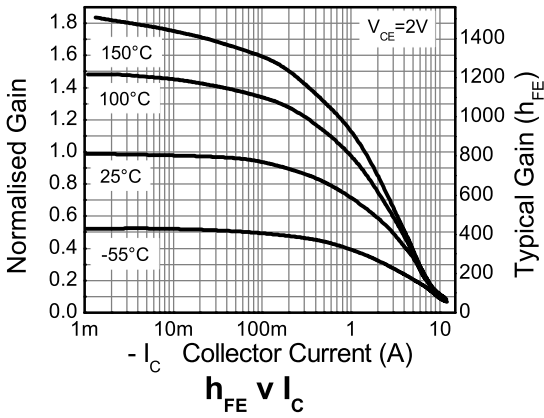
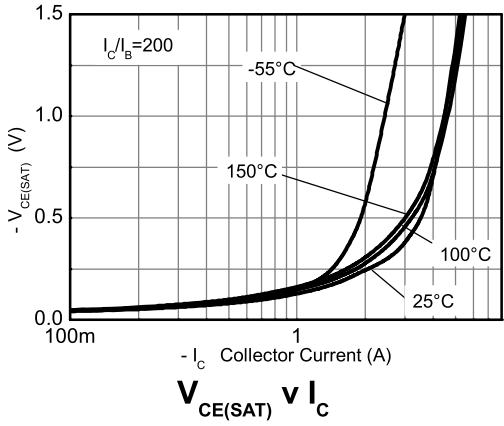
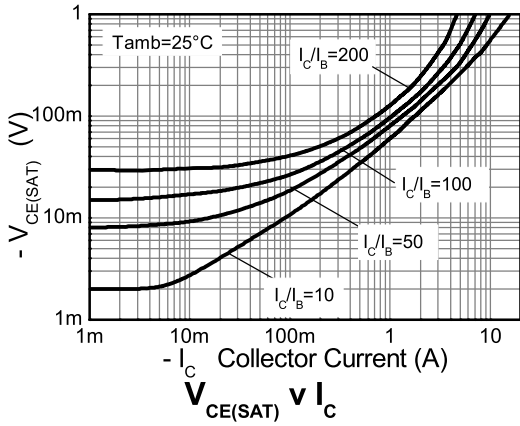
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-base breakdown voltage	BV_{CBO}	-12	-23		V	$I_C = -100\mu\text{A}$
Collector-emitter breakdown voltage (base open)	BV_{CEO}	-12	-16		V	$I_C = -10\text{mA}^{(*)}$ *
Emitter-base breakdown voltage	BV_{EBO}	-7	-8.4		V	$I_E = -100\mu\text{A}$
Collector-base cut-off current	I_{CBO}		<-1	-50 -20	nA μA	$V_{CB} = -10\text{V}$ $V_{CB} = -10\text{V}, T_{amb} = 100^{\circ}\text{C}$
Emitter-base cut-off current	I_{EBO}		<-1	-50	nA	$V_{EB} = -5.6\text{V}$
Collector-emitter saturation voltage	$V_{CE(sat)}$		-80 -60 -130 -250 -260	-100 -75 -165 -350 -340	mV mV mV mV mV	$I_C = -0.5\text{A}, I_B = -2.5\text{mA}^{(*)}$ $I_C = -1\text{A}, I_B = -100\text{mA}^{(*)}$ $I_C = -1\text{A}, I_B = -5\text{mA}^{(*)}$ $I_C = -2\text{A}, I_B = -10\text{mA}^{(*)}$ $I_C = -4\text{A}, I_B = -80\text{mA}^{(*)}$
Base-emitter saturation voltage	$V_{BE(sat)}$		-945	-1050	mV	$I_C = -4\text{A}, I_B = -80\text{mA}^{(*)}$
Base-emitter turn-on voltage	$V_{BE(on)}$		-850	-950	mV	$I_C = -4\text{A}, V_{CE} = -2\text{V}^{(*)}$
Static forward current transfer ratio	h_{FE}	500 400 230 150	750 570 320 210	1500		$I_C = -10\text{mA}, V_{CE} = -2\text{V}^{(*)}$ $I_C = -1\text{A}, V_{CE} = -2\text{V}^{(*)}$ $I_C = -4\text{A}, V_{CE} = -2\text{V}^{(*)}$ $I_C = -6\text{A}, V_{CE} = -2\text{V}^{(*)}$
Transition frequency	f_T	100	250		MHz	$I_C = -50\text{mA}, V_{CE} = -5\text{V}$ $f = 50\text{MHz}$
Input capacitance	C_{ibo}		223		pF	$V_{CB} = -0.5\text{V}, f = 1\text{MHz}^{(*)}$
Output capacitance	C_{obo}		49	60	pF	$V_{CB} = -8\text{V}, f = 1\text{MHz}^{(*)}$
Delay time	t_d		12.8		ns	$V_{CC} = -10\text{V}.$
Rise time	t_r		15.6		ns	$I_C = -500\text{mA},$
Storage time	t_s		240		ns	$I_{B1} = I_{B2} = -50\text{mA}.$
Fall time	t_f		92.8		ns	

NOTES:

(*) Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

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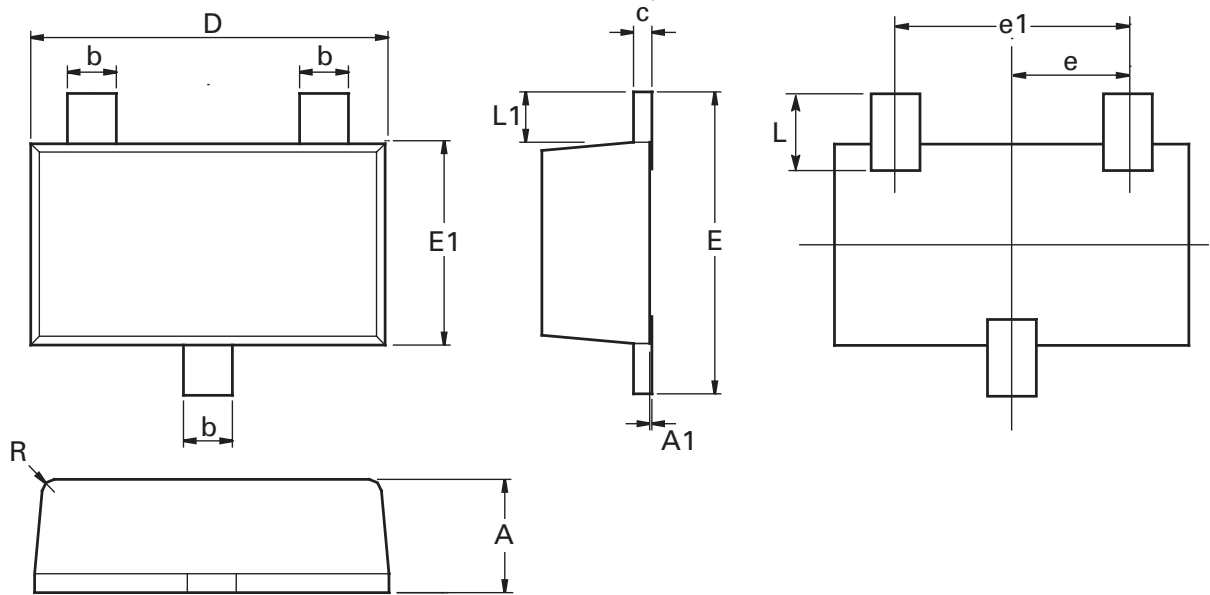
Typical characteristics



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Package outline - SOT23F



Dim.	Millimeters		Inches		Dim.	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Max.	Max.
A	0.80	1.00	0.0315	0.0394	E	2.30	2.50	0.0906	0.0984
A1	0.00	0.10	0.00	0.0043	E1	1.50	1.70	0.0590	0.0669
b	0.35	0.45	0.0153	0.0161	E2	1.10	1.26	0.0433	0.0496
c	0.10	0.20	0.0043	0.0079	L	0.48	0.68	0.0189	0.0268
D	2.80	3.00	0.1102	0.1181	L1	0.30	0.50	0.0153	0.0161
e	0.95 ref		0.0374 ref		R	0.05	0.15	0.0019	0.0059
e1	1.80	2.00	0.0709	0.0787	O	0°	12°	0°	12°

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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